

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

ltc3858iufd-1#pbf

(Engineering Calculation)

QFN 4mm X 5mm Exp. Pad

(printed on: 2020-07-11 22:27:33)

**TOTAL MASS (g) : 0.048725**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.001393	1000000	28588.8984375		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.019997	975000	410403.59375		
		Iron (Fe)	7439-89-6	0.000492	24000	10097.4433594		
		Phosphorus (P)	7723-14-0	0.000006	300	123.139556885		
		Zinc (Zn)	7440-66-6	0.000014	700	287.325622559		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.020509</b>	<b>1000000</b>	<b>420911.53125</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.000227	1000000	4663.04833984		
		<b>External Plating Total:</b>				<b>0.000227</b>	<b>1000000</b>	<b>4663.04833984</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000429	1000000	8804.47753906		
<b>Internal Plating Total:</b>				<b>0.000429</b>	<b>1000000</b>	<b>8804.47753906</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.000709	750000	14550.9892578		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000236	250000	4843.48925781		
<b>Die Attach Total:</b>				<b>0.000945</b>	<b>1000000</b>	<b>19394.4785156</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.003244	130000	66577.453125		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.021457	860000	440367.5625		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000250	10000	5130.81494141		
		<b>Encapsulation Total:</b>				<b>0.024951</b>	<b>1000000</b>	<b>512075.84375</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000271	1000000	5561.80322266		
					<b>TOTAL MASS (g) :</b>	<b>0.048725</b>		